

Sub 17
§ 1

35. (Amended) A method of cutting a substrate of a semiconductor device constructed by arranging a plurality of substrates, on each of which, thin film semiconductor elements two-dimensionally arranged are installed, said method comprising the steps of:

cutting a substrate along at least a slice line provided on the substrate and on a side facing another substrate, which is one of the substrates when the plurality of substrates are arranged, while detecting a misalignment of a cutting position from the slice line and correcting a cutting position;

cutting the substrate of a side opposing the slice line without correcting the cutting position; and

adjacently arranging the plurality of substrates on substantially a same plane such that the sides having been cut face each other, while correcting the cutting position of the substrates.

36. The method according to claim 35, wherein the substrates are fixed on a stage having a groove corresponding to the slice line to cut the substrates.

37. The method according to claim 35, further comprising providing a monitor line on the side where the thin film semiconductor elements are installed, and electrically checking the monitor line after the cutting step is completed.

38. The method according to claim 35, further comprising providing a guide line on the substrate and correcting the cutting position using the guideline.

39. The method according to claim 35, wherein the slice line comprises an electrode layer constituting the thin film semiconductor element.

40. A method of cutting a substrate of a semiconductor device constructed by adjacently arranging a plurality of substrates on substantially a same plane, on each of the substrates, two-dimensionally arranged thin film semiconductor elements are installed, said method comprising the steps of:

cutting at least a slice line provided on the substrate and on a side opposing another substrate, which is one of the substrates when the plurality of substrates are arranged, while detecting a misalignment of a cutting position from the slice line and correcting a cutting position;

cutting the substrate on a side opposing the slice line without correcting the cutting position; and

electrically checking, after the cutting step is completed, a monitor line provided on a side where the thin film semiconductor elements are installed.

41. The method according to claim 40, wherein the substrates are fixed on a stage having a groove corresponding to the slice line to cut the substrates.